

## **TPC8211-VB Datasheet Dual N-Channel 30-V (D-S) MOSFET**

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
30	0.022 at V <sub>GS</sub> = 10 V	6.8	15 nC			
30	0.026 at V <sub>GS</sub> = 4.5 V	6.0	10110			

# SO-8 $D_1$ $D_2$

Top View

#### **FEATURES**

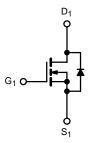
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % UIS Tested
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

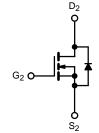


COMPLIANT HALOGEN **FREE** 

#### **APPLICATIONS**

- Set Top Box
- Low Current DC/DC





N-Channel MOSFET

N-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage		$V_{GS}$	± 20	V
	T <sub>C</sub> = 25 °C		6.8 <sup>a</sup>	
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	]	5.6	
Continuous Brain Gunerit (1) = 100 G)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	6.2 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C	1 -	5.2 <sup>b, c</sup>	Α
Pulsed Drain Current	I <sub>DM</sub>	30	^	
Octions October Desire Disable October	T <sub>C</sub> = 25 °C	l-	2.25	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	ls –	1.48 <sup>b, c</sup>	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	5	
Single Pulse Avalanche Energy	L=0.11IIII	E <sub>AS</sub>	1.25	mJ
	T <sub>C</sub> = 25 °C		2.7	
Maximum Dawar Dissination	T <sub>C</sub> = 70 °C	$P_{D}$	1.77	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		1.78 <sup>b, c</sup>	VV
	T <sub>A</sub> = 70 °C	1	1.14 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a, c, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	58	70	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{th,IF}$	38	45	J 5/VV		

#### Notes:

- a. Package limited, T<sub>C</sub> = 25 °C.
  b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 110 °C/W.

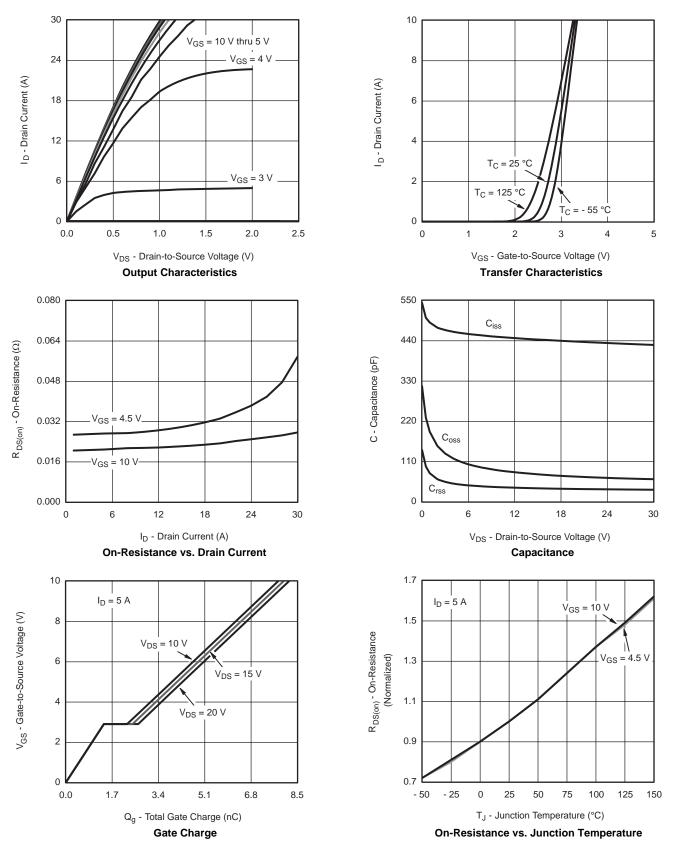


Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			•			•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		32			
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 5.0		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = 250 \mu A$	1.0		2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Oata Valla va Daria Oamaal	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
	5	$V_{GS} = 10 \text{ V, } I_D = 5 \text{ A}$		0.022			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$		0.026		Ω	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		16		S	
Dynamic <sup>b</sup>	<u> </u>		1		l	l	
Input Capacitance	C <sub>iss</sub>			586		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		117			
Reverse Transfer Capacitance	C <sub>rss</sub>			55			
Total Cata Chausa	Q <sub>g</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		15			
Total Gate Charge				3.7	5.6	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		1.4			
Gate-Drain Charge	$Q_{gd}$			1.05			
Gate Resistance	$R_g$	f = 1 MHz	0.8	4.3	8.6	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			12	24		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 3 $\Omega$		55	100		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 5$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		11	22		
Fall Time	t <sub>f</sub>			8	16		
Turn-On Delay Time	t <sub>d(on)</sub>			4	8	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 3 $\Omega$		9	18		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 5$ A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		10	20		
Fall Time	t <sub>f</sub>			6	12		
<b>Drain-Source Body Diode Characteristic</b>	s					_	
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			2.25	۸	
Pulse Diode Forward Current	I <sub>SM</sub>				24	Α	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 2 A, V <sub>GS</sub> = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			11	20	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L _ E A dl/dt _ 100 A/::2 T _ 25 °C		4	8	nC	
Reverse Recovery Fall Time	ta	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		7			
Reverse Recovery Rise Time	t <sub>b</sub>			4		ns	

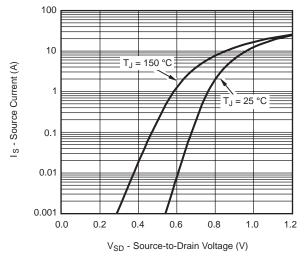
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

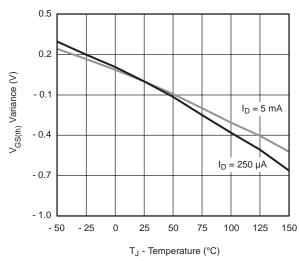




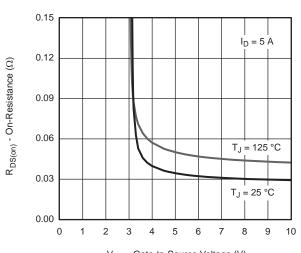




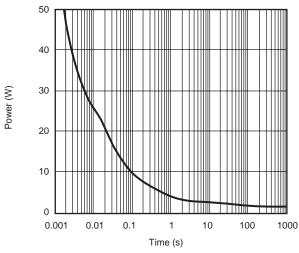
#### Source-Drain Diode Forward Voltage



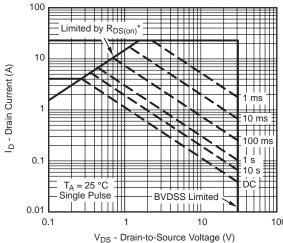
#### **Threshold Voltage**



 $\label{eq:VGS} \mbox{V}_{\mbox{GS}} \mbox{- Gate-to-Source Voltage (V)} \\ \mbox{On-Resistance vs. Gate-to-Source Voltage}$ 



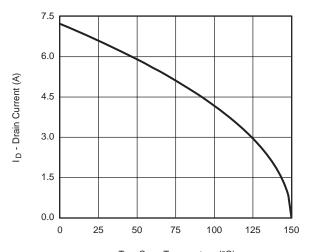
Single Pulse Power



\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

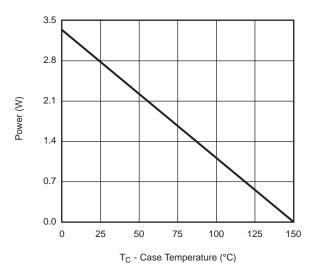
Safe Operating Area, Junction-to-Ambient



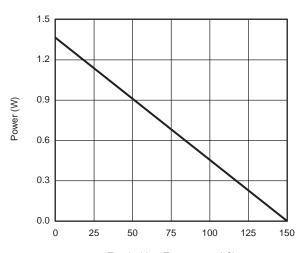


T<sub>C</sub> - Case Temperature (°C)

#### **Current Derating\***



Power, Junction-to-Foot



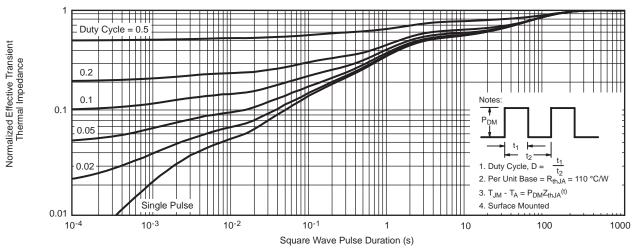
T<sub>A</sub> - Ambient Temperature (°C)

Power, Junction-to-Ambient

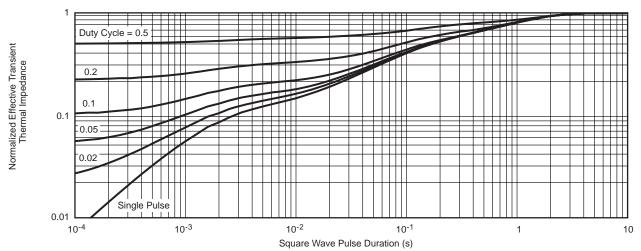
服务热线:400-655-8788 5

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





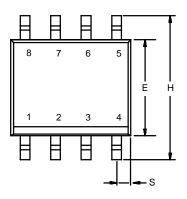
Normalized Thermal Transient Impedance, Junction-to-Ambient

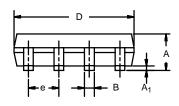


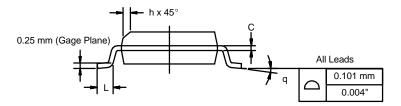
Normalized Thermal Transient Impedance, Junction-to-Foot



**SOIC (NARROW): 8-LEAD**JEDEC Part Number: MS-012







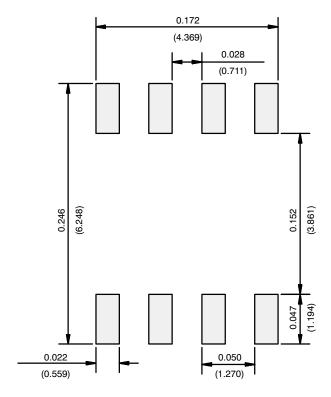
	MILLIM	IETERS	INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Pey I 11-Sep-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



#### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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